



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

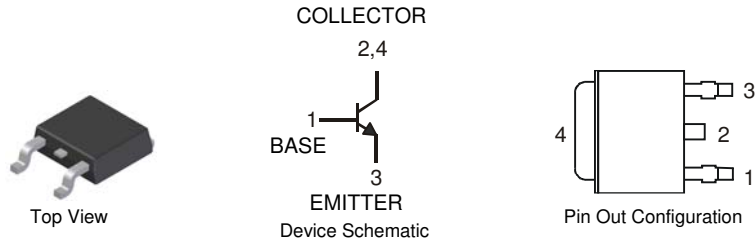


HIGH VOLTAGE NPN SURFACE MOUNT TRANSISTOR
Features

- Epitaxial Planar Die Construction
- High Collector-Emitter Voltage
- Ideally Suited for Automated Assembly Processes
- Ideal for Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: DPAK
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish — Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.34 grams (approximate)


Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	300	V
Collector-Emitter Voltage	V _{CEO}	300	V
Emitter-Base Voltage	V _{EBO}	3	V
Continuous Collector Current	I _C	0.5	A
Peak Pulse Collector Current	I _{CM}	0.75	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @T _C = 25°C	P _D	15	W
Thermal Resistance, Junction to Case	R _{θJC}	8.33	°C/W
Power Dissipation @T _A = 25°C (Note 3)	P _D	1.56	W
Thermal Resistance, Junction to Ambient	R _{θJA}	80	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)						
Collector-Emitter Sustaining Voltage	V _{(SUS)CEO}	300	—	—	V	I _C = 1mA, I _B = 0
Collector Cutoff Current	I _{CBO}	—	—	100	μA	V _{CB} = 300V, I _E = 0
Emitter Cutoff Current	I _{EBO}	—	—	100	μA	V _{EB} = 3V, I _C = 0
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h _{FE}	30	—	240	—	V _{CE} = 10V, I _C = 50mA

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB with minimum recommended pad layout.
 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

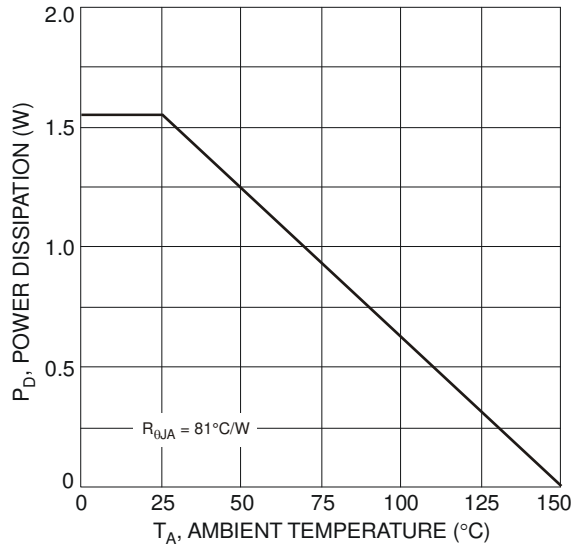


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

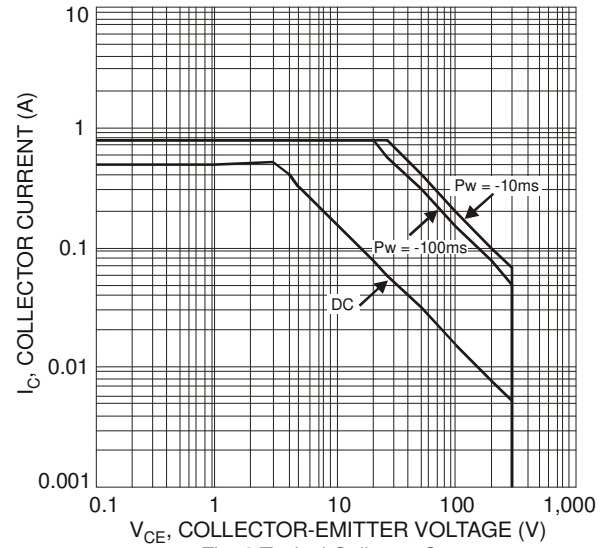


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage (Note 3)

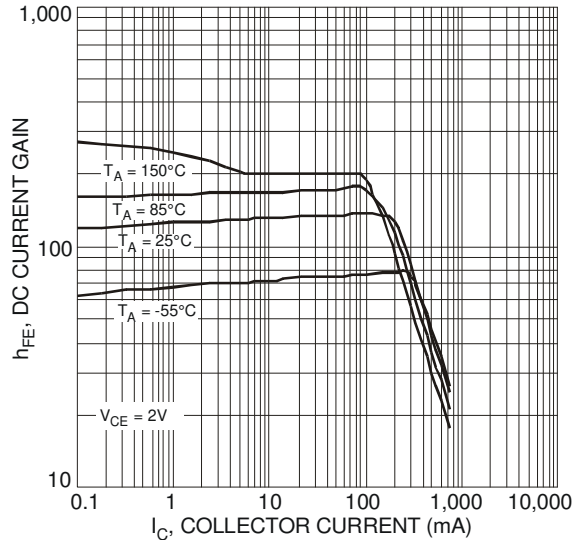


Fig. 3 Typical DC Current Gain vs. Collector Current

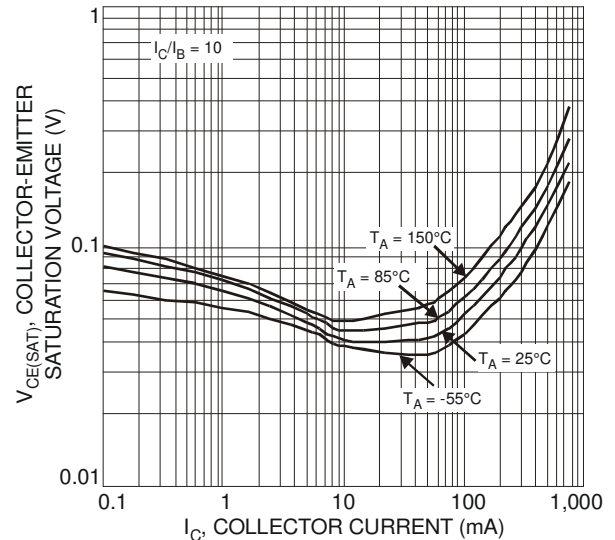


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

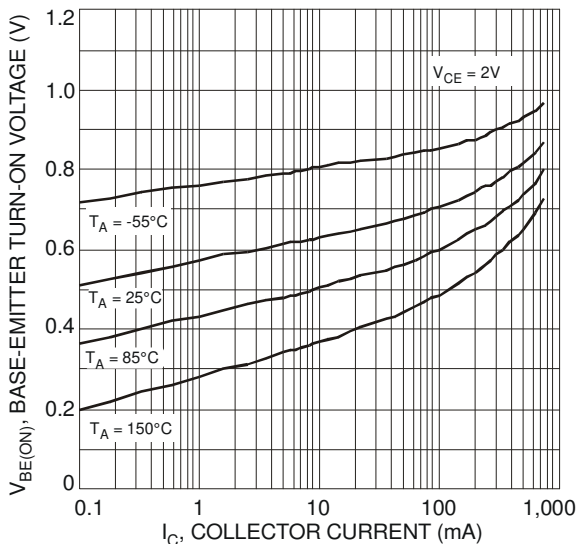


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

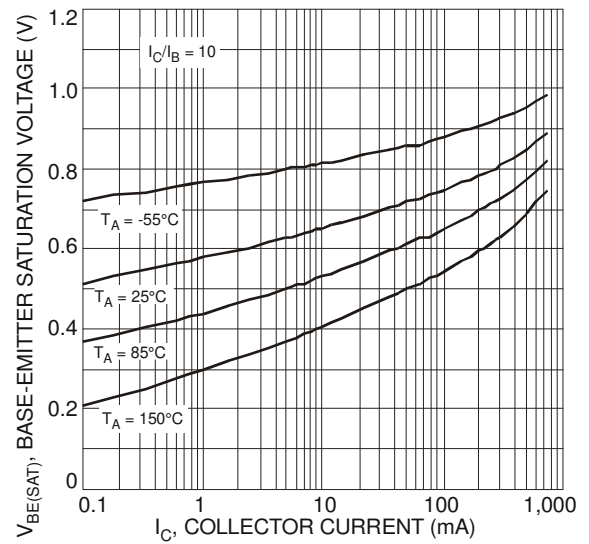


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

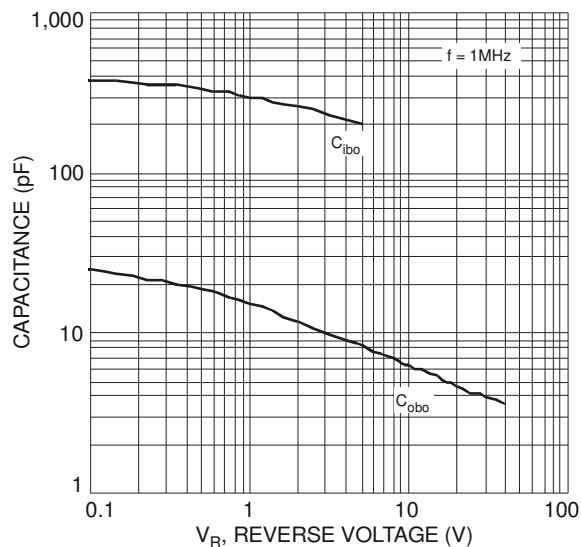


Fig. 7 Typical Capacitance Characteristics

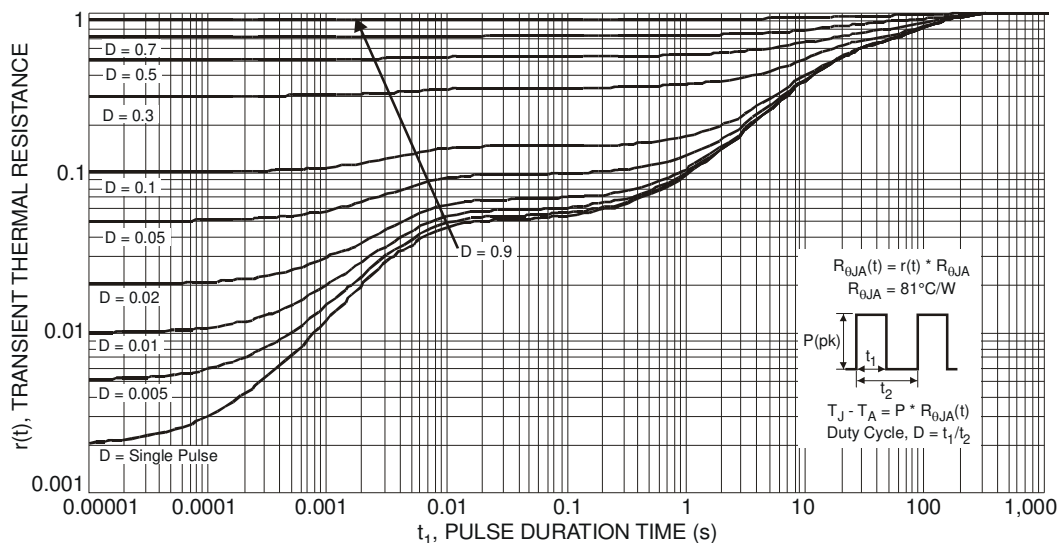


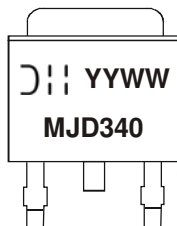
Fig. 8 Transient Thermal Response (Note 3)

Ordering Information (Note 5)

Part Number	Case	Packaging
MJD340-13	DPAK	2500/Tape & Reel

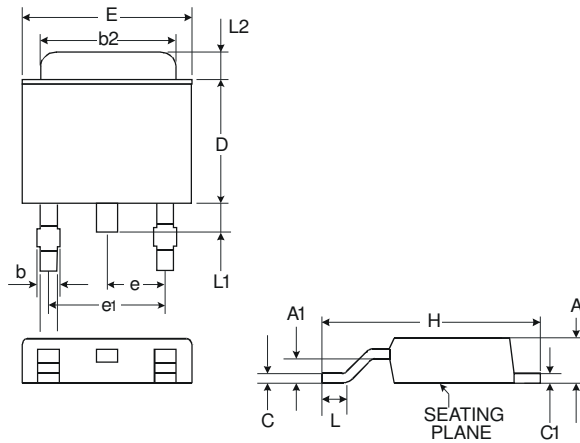
 Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



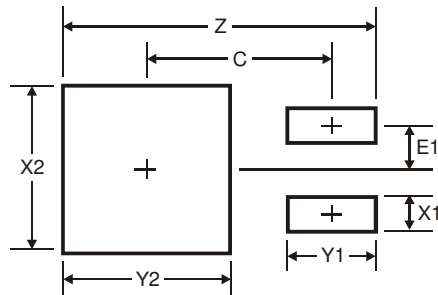
MJD340 = Product Type Marking Code
 DIII = Manufacturers' code marking
 YYWW = Date Code Marking
 YY = Last Digit of Year (ex: 08 = 2008)
 WW = Week Code 01-52

Package Outline Dimensions



DPAK		
Dim	Min	Max
A	2.18	2.40
A1	0.89	1.14
b	0.61 Typ	
b2	5.20	5.50
C	0.45	0.58
C1	0.45	0.58
D	5.40	6.20
E	6.35	6.80
e	2.28 Typ	
e1	4.57 Typ	
H	9.00	10.40
L	0.51	—
L1	0.64	1.02
L2	0.88	1.27
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.